



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
United States Patent and Trademark Office  
Address: COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231  
[www.uspto.gov](http://www.uspto.gov)

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
08/691,434	08/02/1996	SHUNPEI YAMAZAKI	0756-1551	2240

22204 7590 01/15/2002

NIXON PEABODY, LLP  
8180 GREENSBORO DRIVE  
SUITE 800  
MCLEAN, VA 22102

EXAMINER

WILCZEWSKI, MARY A

ART UNIT

PAPER NUMBER

2822

DATE MAILED: 01/15/2002

Please find below and/or attached an Office communication concerning this application or proceeding.

## Office Action Summary

Application No. <b>08/691,434</b>	Applicant(s) <b>Yamazaki et al.</b>
Examiner <b>Mary Wilczewski</b>	Art Unit <b>2822</b>



-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE three MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136 (a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

### Status

- 1)  Responsive to communication(s) filed on Sep 26, 2001 and Oct 24, 2001
- 2a)  This action is FINAL.      2b)  This action is non-final.
- 3)  Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11; 453 O.G. 213.

### Disposition of Claims

- 4)  Claim(s) 16-20, 24, 25, 56-61, and 74-91 is/are pending in the application.
- 4a) Of the above, claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5)  Claim(s) \_\_\_\_\_ is/are allowed.
- 6)  Claim(s) 16-20, 24, 25, 56-61, and 74-91 is/are rejected.
- 7)  Claim(s) \_\_\_\_\_ is/are objected to.
- 8)  Claims \_\_\_\_\_ are subject to restriction and/or election requirement.

### Application Papers

- 9)  The specification is objected to by the Examiner.
- 10)  The drawing(s) filed on \_\_\_\_\_ is/are objected to by the Examiner.
- 11)  The proposed drawing correction filed on \_\_\_\_\_ is: a)  approved b)  disapproved.
- 12)  The oath or declaration is objected to by the Examiner.

### Priority under 35 U.S.C. § 119

- 13)  Acknowledgement is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d).

a)  All b)  Some\* c)  None of:

1.  Certified copies of the priority documents have been received.
2.  Certified copies of the priority documents have been received in Application No. 08/160,909.
3.  Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\*See the attached detailed Office action for a list of the certified copies not received.

- 14)  Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).

### Attachment(s)

- 15)  Notice of References Cited (PTO-892)      18)  Interview Summary (PTO-413) Paper No(s). \_\_\_\_\_
- 16)  Notice of Draftsperson's Patent Drawing Review (PTO-948)      19)  Notice of Informal Patent Application (PTO-152)
- 17)  Information Disclosure Statement(s) (PTO-1449) Paper No(s). 58      20)  Other: \_\_\_\_\_

Art Unit: 1107

## **DETAILED ACTION**

### ***Request for Continued Examination***

A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on September 26, 2001, has been entered.

### ***Priority***

Acknowledgment is made of applicant's claim for foreign priority under 35 U.S.C. 119(a)-(d). The certified copy has been filed in parent Application No. 08/160,909, filed on February 18, 1994.

### ***Claim Rejections - 35 USC § 103***

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Art Unit: 1107

**Claims 16-20, 24, 25, 80 and 86 are rejected under 35 U.S.C. 103(a) as being unpatentable over Begin et al. in view of Miyachi et al., Nakayama et al., and Kawasaki et al., further in view of Codama, all of record, further in view of Pressley, U.S. Patent 4,475,027, further in view of Kawachi et al., the article entitled "Large-Area Process for Fabrication of Poly-Si Thin Film Transistors Using Bucket Ion Source and XeCl Excimer Laser Annealing", newly cited.**

Begin et al. disclose an apparatus for processing semiconductor wafers which includes satellite reaction chambers 60, 62, 64, and 66 disposed around the periphery of central chamber 14, see figure 1. A robot assembly 16 comprising arms 18, 20, and 22 is disposed in central chamber 14. Assembly 16 moves the substrate 12 to any position within the apparatus. Begin et al. lack anticipation only of disclosing that reaction chambers 60, 62, 64, and 66 comprise an ion introducing apparatus and a laser processing apparatus. However, apparatuses used for irradiating an amorphous silicon layer for dehalogenating and hydrogenating the layer, etching, and plasma doping are well known in the art, see Miyachi et al., Kawasaki et al., and Nakayama et al., respectively.

Miyachi et al., in particular, disclose an apparatus which comprises a film-forming chamber 1 for forming an amorphous semiconductor film and a dehalogenating-hydrogenating chamber 2, see figure 5, for example. The two chambers are combined by a conveying device 13. The substrates 10 move between the two chambers without being exposed to

Art Unit: 1107

outside air. Note in Example 14 that the dehalogenation-hydrogenation is preferably performed in a processing chamber by light irradiation using, for example, an ultraviolet laser, a visible light laser, or a carbon dioxide laser, see column 18, lines 29-43. Miyachi et al. lack anticipation only of using a rectangular-shaped laser beam having an elongated cross-section and of moving the substrate in a direction orthogonal to the laser beam during the irradiating step.

Pressley discloses an laser processing apparatus which comprises a rectangularly-shaped laser beam in which the laser beam is scanned by moving the beam relative to the substrate, see column 7, lines 4-9. Since the apparatus of Pressley permits uniform laser irradiation of semiconducting materials, it would have been obvious to one of ordinary skill in the art to use a laser beam having a rectangular cross-section in the dehalogenating-hydrogenating chamber of Miyachi et al. In addition, it is obvious from the teachings of Pressley that the substrates could be alternatively moved with respect to the laser beam in the known apparatus of Miyachi et al.

Codama discloses a method of fabricating a thin film transistor which includes the steps of depositing an amorphous silicon layer; etching the silicon layer, the gate layer and the gate insulating layer; plasma doping the silicon layer to form source and drain regions, see column 1, lines 42-46; and hydrogenating the silicon layer. Therefore, in light of the semiconductor device manufacturing process of Codama, it would have been obvious to the skilled artisan to include a

Art Unit: 1107

laser processing apparatus and an ion introducing apparatus in the known multi-chambered apparatus of Begin et al. in order to fabricate the thin film transistor of Codama.

Although Codama teaches plasma doping of a semiconductor film, Codama fails to anticipate the use of an ion introducing apparatus comprising a grid electrode around which a dopant is made a plasma and accelerated toward the semiconductor layer. However, a plasma doping apparatus which comprises a grid electrode is known in the art, as taught by Kawachi et al., see Fig. 1. In addition, Kawachi et al. teach the activation of the implanted ions by laser annealing. Since Kawachi et al. teach that the disclosed ion introducing apparatus is applicable to polycrystalline thin film transistors and permits large-area implantation, it would have been obvious to one skilled in the art to include the ion introducing apparatus of Kawachi et al. in the known multi-chambered apparatus of Begin et al. in order to perform large-area doping or polysilicon in the fabrication of the device of Codama. Since Kawachi et al. teach laser annealing of the dopants implanted using the disclosed large-area doping apparatus shown in Fig. 1, it would have been obvious to the skilled artisan to include the ion introducing apparatus of Kawachi et al. in a multi-chambered apparatus that includes a laser irradiation chamber.

**Claims 56-61, 81 and 87 are rejected under 35 U.S.C. 103(a) as being unpatentable over Begin et al. in view of Miyachi et al., Nakayama et al., and Kawasaki et al., further in view of Codama, all of record, further in view of Hashizume, JP 03-286518, further in view of Kawachi et al., the article entitled “Large-Area Process for Fabrication of Poly-Si**

**Thin Film Transistors Using Bucket Ion Source and XeCl Excimer Laser Annealing",  
newly cited.**

Begin et al. disclose an apparatus for processing semiconductor wafers which includes satellite reaction chambers 60, 62, 64, and 66 disposed around the periphery of central chamber 14, see figure 1. A robot assembly 16 comprising arms 18, 20, and 22 is disposed in central chamber 14. Assembly 16 moves the substrate 12 to any position within the apparatus. Begin et al. lack anticipation only of disclosing that reaction chambers 60, 62, 64, and 66 comprise an ion introducing apparatus and a laser processing apparatus. However, apparatuses used for irradiating an amorphous silicon layer for dehalogenating and hydrogenating the layer, etching, and plasma doping are well known in the art, see Miyachi et al., Kawasaki et al., and Nakayama et al., respectively.

Miyachi et al., in particular, disclose an apparatus which comprises a film-forming chamber 1 for forming an amorphous semiconductor film and a dehalogenating-hydrogenating chamber 2, see figure 5, for example. The two chambers are combined by a conveying device 13. The substrates 10 move between the two chambers without being exposed to outside air. Note in Example 14 that the dehalogenation-hydrogenation is preferably performed in a processing chamber by light irradiation using, for example, an ultraviolet laser, a visible light laser, or a carbon dioxide laser, see column 18, lines 29-43. Miyachi et al. lack anticipation only of using a rectangular-shaped laser beam having an elongated cross-section

Art Unit: 1107

and of moving the substrate in a direction orthogonal to the laser beam during the irradiating step.

Hashizume discloses a laser processing apparatus which comprises a laser beam having a rectangular shape in which the laser beam is scanned by moving the beam relative to the substrate, see figure 2 and pages 7-9 of the translation. Note in figure 4, Hashizume shows that a rectangular-shaped laser beam having a width greater than a "substantially" square substrate is scanned along the substrate surface. The use of a rectangularly-shaped laser beam, as in the method of Hashizume, eliminates overlapping regions and permits uniform irradiation of the silicon layer, see page 7 of the translation. Since the rectangular-shaped laser beam of Hashizume permits uniform laser irradiation of semiconducting materials, it would have been obvious to one of ordinary skill in the art to use a laser beam having a rectangular cross-section in the dehalogenating-hydrogenating chamber of Miyachi et al. In addition, it is obvious from the teachings of Hashizume that the substrates could be moved with respect to the laser beam in the known apparatus of Miyachi et al. It is noted that Hashizume does not disclose the dimensions of either the substrate or laser beam, however, in light of the generic teaching of Hashizume to use a rectangularly-shaped laser beam having a width greater than that of the irradiated substrate, these dimensions are not deemed to patentably distinguish the claimed method from that of Hashizume. In addition, Hashizume discloses a laser beam scanning technique, however, it would have been obvious to one of ordinary skill in the art that, alternatively, the substrate could be moved with respect to the laser beam.

Art Unit: 1107

Codama discloses a method of fabricating a thin film transistor which includes the steps of depositing an amorphous silicon layer; etching the silicon layer, the gate layer and the gate insulating layer; plasma doping the silicon layer to form source and drain regions, see column 1, lines 42-46; and hydrogenating the silicon layer. Therefore, in light of the semiconductor device manufacturing process of Codama, it would have been obvious to the skilled artisan to include a laser processing apparatus and an ion introducing apparatus in the known multi-chambered apparatus of Begin et al. in order to fabricate the thin film transistor of Codama.

Although Codama teaches plasma doping of a semiconductor film, Codama fails to anticipate the use of an ion introducing apparatus comprising a grid electrode around which a dopant is made a plasma and accelerated toward the semiconductor layer. However, a plasma doping apparatus which comprises a grid electrode is known in the art, as taught by Kawachi et al., see Fig. 1. In addition, Kawachi et al. teach the activation of the implanted ions by laser annealing. Since Kawachi et al. teach that the disclosed ion introducing apparatus is applicable to polycrystalline thin film transistors and permits large-area implantation, it would have been obvious to one skilled in the art to include the ion introducing apparatus of Kawachi et al. in the known multi-chambered apparatus of Begin et al. in order to perform large-area doping or polysilicon in the fabrication of the device of Codama. Since Kawachi et al. teach laser annealing of the dopants implanted using the disclosed large-area doping apparatus shown in Fig. 1, it would have been obvious to the skilled artisan to include the ion introducing apparatus of Kawachi et al. in a multi-chambered apparatus that includes a laser irradiation chamber.

Art Unit: 1107

**Claims 74-79, 82-85, and 89-91 are rejected under 35 U.S.C. 103(a) as being unpatentable over Begin et al. in view of Miyachi et al., Nakayama et al., and Kawasaki et al., further in view of Codama, all of record, further in view of Kawachi et al., the article entitled “Large-Area Process for Fabrication of Poly-Si Thin Film Transistors Using Bucket Ion Source and XeCl Excimer Laser Annealing”, newly cited.**

Begin et al. disclose an apparatus for processing semiconductor wafers which includes satellite reaction chambers 60, 62, 64, and 66 disposed around the periphery of central chamber 14, see figure 1. A robot assembly 16 comprising arms 18, 20, and 22 is disposed in central chamber 14. Assembly 16 moves the substrate 12 to any position within the apparatus. Begin et al. lack anticipation only of disclosing that reaction chambers 60, 62, 64, and 66 comprise an ion introducing apparatus and a laser processing apparatus. However, apparatuses used for irradiating an amorphous silicon layer for dehalogenating and hydrogenating the layer, etching, and plasma doping are well known in the art, see Miyachi et al., Kawasaki et al., and Nakayama et al., respectively.

Miyachi et al., in particular, disclose an apparatus which comprises a film-forming chamber 1 for forming an amorphous semiconductor film and a dehalogenating-hydrogenating chamber 2, see figure 5, for example. The two chambers are combined by a conveying device 13. The substrates 10 move between the two chambers without being exposed to outside air. Note in Example 14 that the dehalogenation-hydrogenation is preferably performed in a processing chamber by light irradiation using, for example, an ultraviolet laser,

Art Unit: 1107

a visible light laser, or a carbon dioxide laser, see column 18, lines 29-43. Miyachi et al. lack anticipation only of using a rectangular-shaped laser beam having an elongated cross-section and of moving the substrate in a direction orthogonal to the laser beam during the irradiating step.

Codama discloses a method of fabricating a thin film transistor which includes the steps of depositing an amorphous silicon layer; etching the silicon layer, the gate layer and the gate insulating layer; plasma doping the silicon layer to form source and drain regions, see column 1, lines 42-46; and hydrogenating the silicon layer. Therefore, in light of the semiconductor device manufacturing process of Codama, it would have been obvious to the skilled artisan to include a laser processing apparatus and an ion introducing apparatus in the known multi-chambered apparatus of Begin et al. in order to fabricate the thin film transistor of Codama.

Although Codama teaches plasma doping of a semiconductor film, Codama fails to anticipate the use of an ion introducing apparatus comprising a grid electrode around which a dopant is made a plasma and accelerated toward the semiconductor layer. However, a plasma doping apparatus which comprises a grid electrode is known in the art, as taught by Kawachi et al., see Fig. 1. In addition, Kawachi et al. teach the activation of the implanted ions by laser annealing. Since Kawachi et al. teach that the disclosed ion introducing apparatus is applicable to polycrystalline thin film transistors and permits large-area implantation, it would have been obvious to one skilled in the art to include the ion introducing apparatus of Kawachi et al. in the known multi-chambered apparatus of Begin et al. in order to perform large-area doping or

Art Unit: 1107

polysilicon in the fabrication of the device of Codama. Since Kawachi et al. teach laser annealing of the dopants implanted using the disclosed large-area doping apparatus shown in Fig. 1, it would have been obvious to the skilled artisan to include the ion introducing apparatus of Kawachi et al. in a multi-chambered apparatus that includes a laser irradiation chamber.

***Response to Arguments***

Applicants' arguments filed September 26, 2001, have been fully considered but they are not persuasive.

Applicants have argued that the cited prior art references, applied separately or in combination, fail to teach, disclose, or suggest Applicants' claimed invention as recited in the pending claims. Applicants have further argued that in order to show obviousness, all limitations of a claim must be taught or suggested by the prior art. Moreover, Applicants point out that it is error to ignore specific limitations distinguishing over the references. However, Applicants have failed to point out which limitations are not taught by the applied prior art or which limitations have been ignored by the Examiner. Hence, it is maintained that each and every limitation of the pending claims has been addressed by the Examiner. In addition, Applicants have argued that obviousness cannot be established by combining the teachings of the prior art to produce the claimed invention, absent some teaching, suggestion, or incentive supporting the combination. However, again Applicants have failed to specifically point out the deficiencies of the Examiner's rejection. It is not sufficient simply for Applicants to cite generalized allegations of deficiencies in

Art Unit: 1107

the Examiner's rejection, rather Applicants must specifically point out what limitations of the pending claims are not taught by the cited references and where in the Examiner's rejection there is a lack of motivation, suggestion, or incentive for supporting the combination of references. Absent any showing by Applicants, it is maintained that motivation for the combination of the applied references is clearly set forth in the rejections *supra*.

***Conclusion***

Any inquiry concerning this communication or earlier communications from the examiner should be directed to M. Wilczewski whose telephone number is (703) 308-2771.



M. Wilczewski  
Primary Examiner  
Tech Center 2800

MW

January 10, 2002